



IPC Class II Assembly

## Layer Stack Up Detail for: roneCPUBoard-v15a.PcbDoc

Layer Name	Gerber Document	Copper Thickness	Dielectric Height	Dielectric Material	Dielectric Constant	Dielectric Type
Top Solder Mask	(.GTS)		0.4mil	Black Solder Resist	3.50	
Top Layer	(.GTL)	1.4mil				
			58.4mil	FR-4	4.80	Core
Bottom Layer	(.GBL)	1.4mil				
Bottom Solder Mask	(.GBS)		0.4mil	Black Solder Resist	3.50	

FR4 0.062

ENIG or Silver Immersion Pad Finish

Symbol	Hit Count	Tool Size	Plated	Hole Type
▽	65	12mil (0.305mm)	PTH	Round
□	16	12.992mil (0.33mm)	PTH	Round
○	347	20mil (0.508mm)	PTH	Round
☆	12	31mil (0.787mm)	NPTH	Round
⊗	50	35mil (0.889mm)	PTH	Round
⊗	12	35.433mil (0.9mm)	PTH	Round
⊕	2	46.85mil (1.19mm)	PTH	Round
□	4	52mil (1.321mm)	PTH	Round
◇	5	59.5mil (1.511mm)	PTH	Round
▽	4	129mil (3.277mm)	PTH	Round
○	2	158mil (4.013mm)	NPTH	Round
	519 Total			